

# DATA SHEET

## **74LV377**

Octal D-type flip-flop with data enable;  
positive edge-trigger

Product specification  
Supersedes data of 1997 Mar 04  
IC24 Data Handbook

1998 Jun 10

# Octal D-type flip-flop with data enable; positive edge-trigger

74LV377

## FEATURES

- Optimized for Low Voltage applications: 1.0 to 3.6V
- Accepts TTL input levels between  $V_{CC} = 2.7V$  and  $V_{CC} = 3.6V$
- Typical  $V_{OLP}$  (output ground bounce)  $< 0.8V @ V_{CC} = 3.3V$ ,  $T_{amb} = 25^{\circ}C$
- Typical  $V_{OHV}$  (output  $V_{OH}$  undershoot)  $> 2V @ V_{CC} = 3.3V$ ,  $T_{amb} = 25^{\circ}C$
- Ideal for addressable register applications
- Data enable for address and data synchronization applications
- Eight positive-edge triggered D-type flip-flops
- Output capability: standard
- $I_{CC}$  category: MSI

## DESCRIPTION

The 74LV377 is a low-voltage CMOS device and is pin and function compatible with 74HC/HCT377.

The 74LV377 has eight edge-triggered, D-type flip-flops with individual D inputs and Q outputs. A common clock (CP) input loads all flip-flops simultaneously when the data enable ( $\bar{E}$ ) is LOW. The state of each D input, one set-up time before the LOW-to-HIGH clock transition, is transferred to the corresponding output ( $Q_n$ ) of the flip-flop. The  $\bar{E}$  input must be stable only one set-up time prior to the LOW-to-HIGH transition for predictable operation.

## QUICK REFERENCE DATA

GND = 0V;  $T_{amb} = 25^{\circ}C$ ;  $t_r = t_f \leq 2.5$  ns

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
$t_{PHL}/t_{PLH}$	Propagation delay CP to $Q_n$	$C_L = 15pF$ $V_{CC} = 3.3V$	13	ns
$f_{max}$	Maximum clock frequency		77	MHz
$C_I$	Input capacitance		3.5	pF
$C_{PD}$	Power dissipation capacitance per flip-flop	Notes 1 and 2	20	pF

### NOTES:

1.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ )  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$  where:  
 $f_i$  = input frequency in MHz;  $C_L$  = output load capacity in pF;  
 $f_o$  = output frequency in MHz;  $V_{CC}$  = supply voltage in V;  
 $\sum (C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.
2. The condition is  $V_I = GND$  to  $V_{CC}$

## ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
20-Pin Plastic DIL	$-40^{\circ}C$ to $+125^{\circ}C$	74LV377 N	74LV377 N	SOT146-1
20-Pin Plastic SO	$-40^{\circ}C$ to $+125^{\circ}C$	74LV377 D	74LV377 D	SOT163-1
20-Pin Plastic SSOP Type II	$-40^{\circ}C$ to $+125^{\circ}C$	74LV377 DB	74LV377 DB	SOT339-1
20-Pin Plastic TSSOP Type I	$-40^{\circ}C$ to $+125^{\circ}C$	74LV377 PW	74LV377PW DH	SOT360-1

## PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1	$\bar{E}$	Data enable input (active-LOW)
2, 5, 6, 9, 12, 15, 16, 19	$Q_0$ to $Q_7$	flip-flop outputs
3, 4, 7, 8, 13, 14, 17, 18	$D_0$ to $D_7$	Data inputs
10	GND	Ground (0V)
11	CP	Clock input (LOW-to-HIGH, edge-triggered)
20	$V_{CC}$	Positive supply voltage

## FUNCTION TABLE

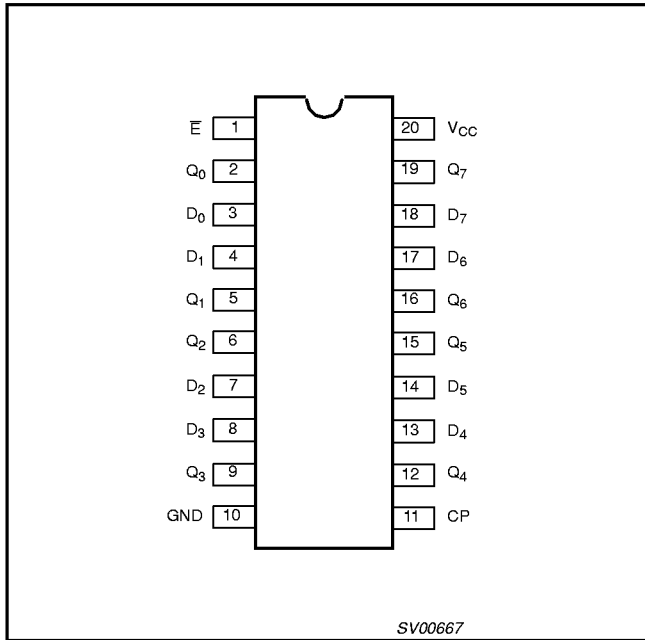
OPERATING MODES	INPUTS			OUTPUTS
	CP	$\bar{E}$	$D_n$	$Q_n$
Load "1"	$\uparrow$	l	h	H
Load "0"	$\uparrow$	l	l	L
Hold (do nothing)	$\uparrow$	h	X	No change
	X	H	X	No change

- H = HIGH voltage level  
h = HIGH voltage level one set-up time prior to the LOW-to-HIGH CP transition  
L = LOW voltage level  
l = LOW voltage level one set-up time prior to the LOW-to-HIGH CP transition  
 $\uparrow$  = LOW-to-HIGH CP transition  
X = Don't care

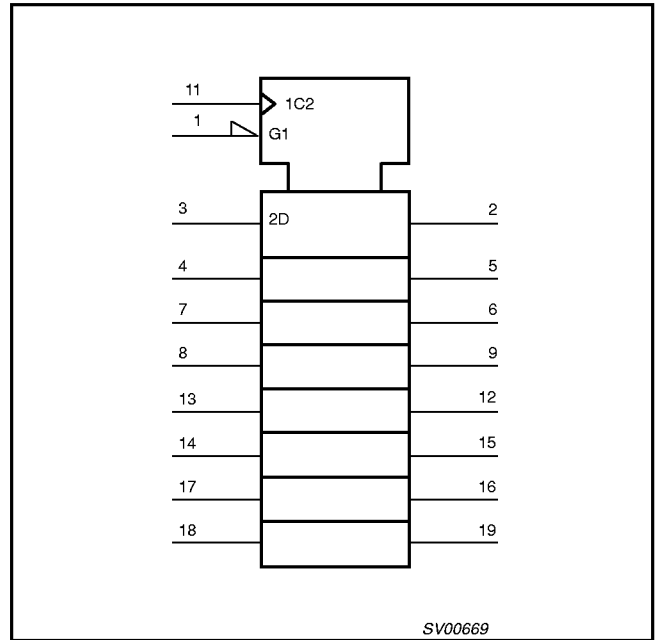
# Octal D-type flip-flop with data enable; positive edge-trigger

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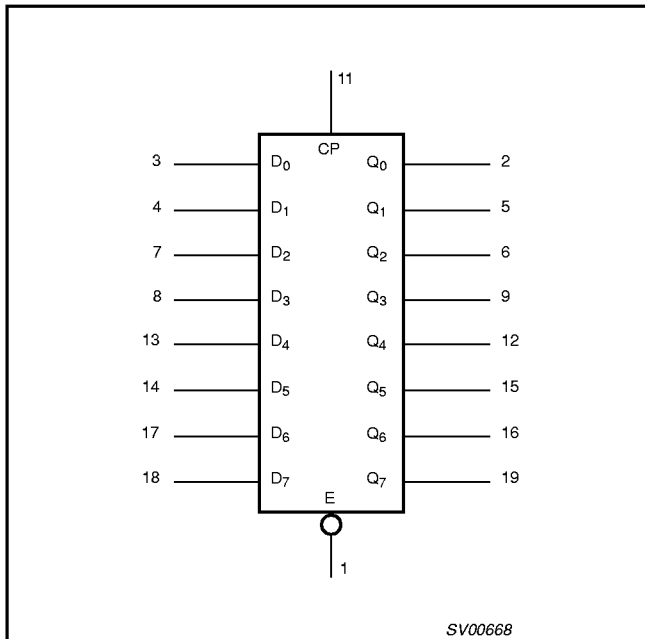
## PIN CONFIGURATION



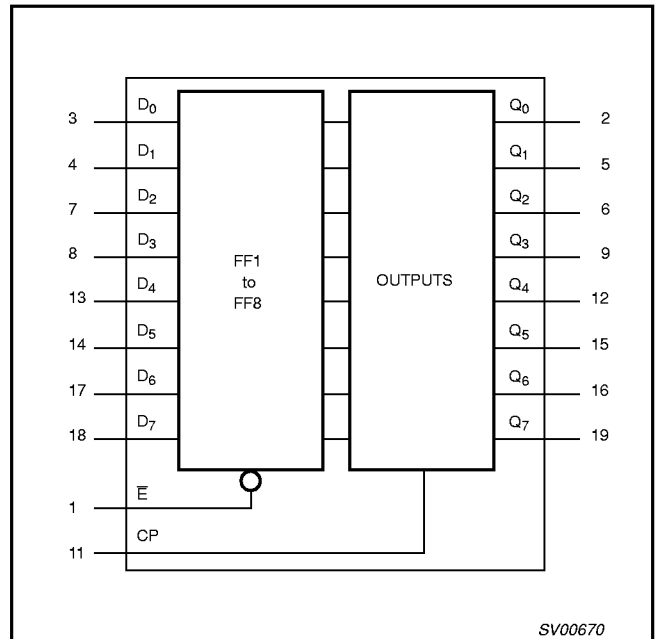
## LOGIC SYMBOL (IEEE/IEC)



## LOGIC SYMBOL



## FUNCTIONAL DIAGRAM



# Octal D-type flip-flop with data enable; positive edge-trigger

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## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
$V_{CC}$	DC supply voltage	See Note 1	1.0	3.3	3.6	V
$V_I$	Input voltage		0	–	$V_{CC}$	V
$V_O$	Output voltage		0	–	$V_{CC}$	V
$T_{amb}$	Operating ambient temperature range in free air	See DC and AC characteristics	–40 –40		+85 +125	°C
$t_r, t_f$	Input rise and fall times	$V_{CC} = 1.0V$ to $2.0V$ $V_{CC} = 2.0V$ to $2.7V$ $V_{CC} = 2.7V$ to $3.6V$	– – –	– – –	500 200 100	ns/V

### NOTE:

- The LV is guaranteed to function down to  $V_{CC} = 1.0V$  (input levels GND or  $V_{CC}$ ); DC characteristics are guaranteed from  $V_{CC} = 1.2V$  to  $V_{CC} = 3.6V$ .

## ABSOLUTE MAXIMUM RATINGS<sup>1, 2</sup>

In accordance with the Absolute Maximum Rating System (IEC 134).

Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
$V_{CC}$	DC supply voltage		–0.5 to +4.6	V
$\pm I_{IK}$	DC input diode current	$V_I < -0.5$ or $V_I > V_{CC} + 0.5V$	20	mA
$\pm I_{OK}$	DC output diode current	$V_O < -0.5$ or $V_O > V_{CC} + 0.5V$	50	mA
$\pm I_O$	DC output source or sink current – standard outputs	$-0.5V < V_O < V_{CC} + 0.5V$	25	mA
$\pm I_{GND},$ $\pm I_{CC}$	DC $V_{CC}$ or GND current for types with –standard outputs		50	mA
$T_{stg}$	Storage temperature range		–65 to +150	°C
$P_{tot}$	Power dissipation per package –plastic DIL –plastic mini-pack (SO) –plastic shrink mini-pack (SSOP and TSSOP)	for temperature range: –40 to +125°C above +70°C derate linearly with 12mW/K above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	750 500 400	mW

### NOTES:

- Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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## DC CHARACTERISTICS FOR THE LV FAMILY

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			-40°C to +85°C			-40°C to +125°C		
			MIN	TYP <sup>1</sup>	MAX	MIN	MAX	
V <sub>IH</sub>	HIGH level Input voltage	V <sub>CC</sub> = 1.2V	0.9			0.9		V
		V <sub>CC</sub> = 2.0V	1.4			1.4		
		V <sub>CC</sub> = 2.7 to 3.6V	2.0			2.0		
V <sub>IL</sub>	LOW level Input voltage	V <sub>CC</sub> = 1.2V			0.3		0.3	V
		V <sub>CC</sub> = 2.0V			0.6		0.6	
		V <sub>CC</sub> = 2.7 to 3.6V			0.8		0.8	
V <sub>OH</sub>	HIGH level output voltage; all outputs	V <sub>CC</sub> = 1.2V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; -I <sub>O</sub> = 100μA		1.2				V
		V <sub>CC</sub> = 2.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; -I <sub>O</sub> = 100μA	1.8	2.0		1.8		
		V <sub>CC</sub> = 2.7V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; -I <sub>O</sub> = 100μA	2.5	2.7		2.5		
		V <sub>CC</sub> = 3.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; -I <sub>O</sub> = 100μA	2.8	3.0		2.8		
	HIGH level output voltage; STANDARD outputs	V <sub>CC</sub> = 3.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; -I <sub>O</sub> = 6mA	2.40	2.82		2.20		
V <sub>OL</sub>	LOW level output voltage; all outputs	V <sub>CC</sub> = 1.2V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = 100μA		0				V
		V <sub>CC</sub> = 2.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = 100μA		0	0.2		0.2	
		V <sub>CC</sub> = 2.7V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = 100μA		0	0.2		0.2	
		V <sub>CC</sub> = 3.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = 100μA		0	0.2		0.2	
	LOW level output voltage; STANDARD outputs	V <sub>CC</sub> = 3.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = 6mA		0.25	0.40		0.50	
I <sub>I</sub>	Input leakage current	V <sub>CC</sub> = 3.6V; V <sub>I</sub> = V <sub>CC</sub> or GND			1.0		1.0	μA
I <sub>CC</sub>	Quiescent supply current; MSI	V <sub>CC</sub> = 3.6V; V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0			20.0		160	μA
ΔI <sub>CC</sub>	Additional quiescent supply current per input	V <sub>CC</sub> = 2.7V to 3.6V; V <sub>I</sub> = V <sub>CC</sub> - 0.6V			500		850	μA

### NOTE:

- All typical values are measured at T<sub>amb</sub> = 25°C.

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## AC CHARACTERISTICS

GND = 0V;  $t_r = t_f \leq 2.5\text{ns}$ ;  $C_L = 50\text{pF}$ ;  $R_L = 1\text{K}\Omega$

SYMBOL	PARAMETER	WAVEFORM	CONDITION	LIMITS					UNIT
				-40 to +85 °C			-40 to +125 °C		
				V <sub>CC</sub> (V)	MIN	TYP <sup>1</sup>	MAX	MIN	
t <sub>PHL</sub> /t <sub>PLH</sub>	Propagation delay CP to Q <sub>n</sub>	Figure 1	1.2	–	80	–	–	–	ns
			2.0	–	27	51	–	61	
			2.7	–	20	38	–	45	
			3.0 to 3.6	–	15 <sup>2</sup>	30	–	36	
t <sub>w</sub>	Clock pulse width HIGH or LOW	Figure 2	2.0	34	9	–	41	–	ns
			2.7	25	6	–	30	–	
			3.0 to 3.6	20	5 <sup>2</sup>	–	24	–	
t <sub>su</sub>	Set-up time D <sub>n</sub> to CP	Figure 2	1.2	–	25	–	–	–	ns
			2.0	22	9	–	26	–	
			2.7	16	6	–	19	–	
			3.0 to 3.6	13	5 <sup>2</sup>	–	15	–	
t <sub>su</sub>	Set-up time $\bar{E}$ to CP	Figure 2	1.2	–	10	–	–	–	ns
			2.0	22	4	–	26	–	
			2.7	16	3	–	19	–	
			3.0 to 3.6	13	2 <sup>2</sup>	–	15	–	
t <sub>h</sub>	Hold time D <sub>n</sub> to CP	Figure 2	1.2	–	–15	–	–	–	ns
			2.0	5	–5	–	5	–	
			2.7	5	–4	–	5	–	
			3.0 to 3.6	5	–3 <sup>2</sup>	–	5	–	
t <sub>h</sub>	Hold time $\bar{E}$ to CP	Figure 2	1.2	–	–5	–	–	–	ns
			2.0	5	–2	–	5	–	
			2.7	5	–2	–	5	–	
			3.0 to 3.6	5	–1 <sup>2</sup>	–	5	–	
f <sub>max</sub>	Maximum clock pulse frequency	Figure 1	2.0	14	40	–	12	–	MHz
			2.7	19	58	–	16	–	
			3.0 to 3.6	24	70 <sup>2</sup>	–	20	–	

### NOTES:

1. Unless otherwise stated, all typical values are at T<sub>amb</sub> = 25°C.
2. Typical value measured at V<sub>CC</sub> = 3.3V.

# Octal D-type flip-flop with data enable; positive edge-trigger

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### AC WAVEFORMS

$V_M = 1.5V$  at  $V_{CC} \geq 2.7V$

$V_M = 0.5V * V_{CC}$  at  $V_{CC} < 2.7V$

$V_{OL}$  and  $V_{OH}$  are the typical output voltage drop that occur with the output load.

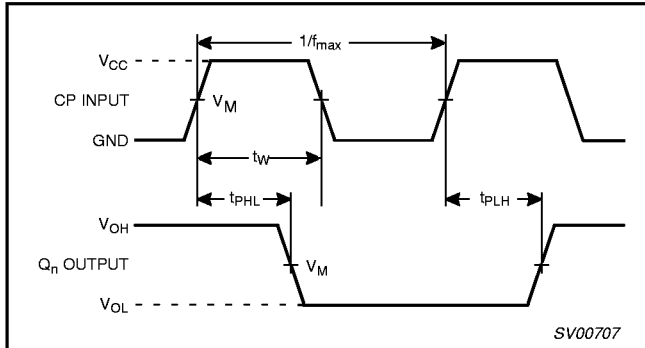


Figure 1. Clock (CP) to output ( $Q_n$ ) propagation delays, the clock pulse width and the maximum clock pulse frequency.

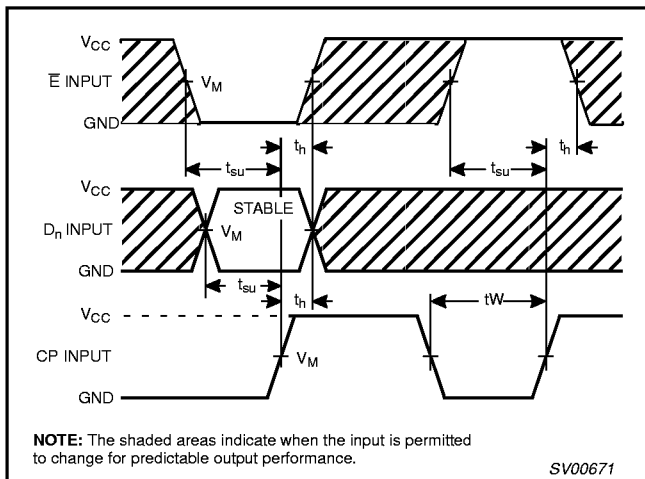


Figure 2. Data set-up and hold times from the data input ( $D_n$ ) and from the enable input ( $\bar{E}$ ) to the clock (CP).

### TEST CIRCUIT

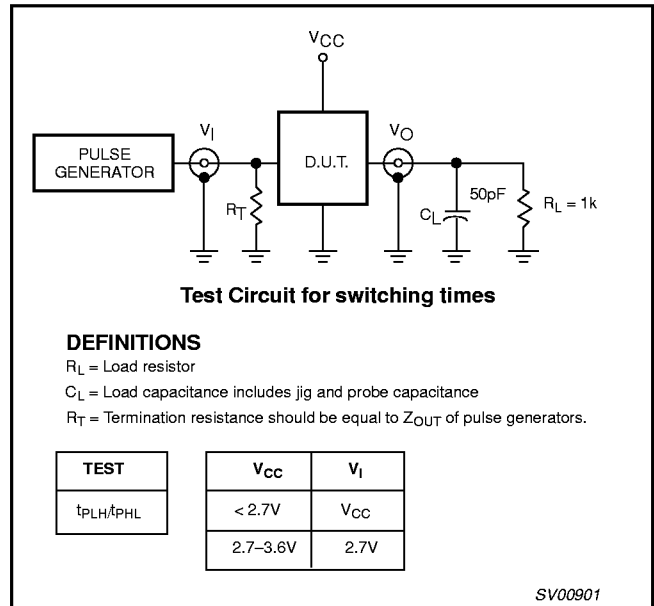


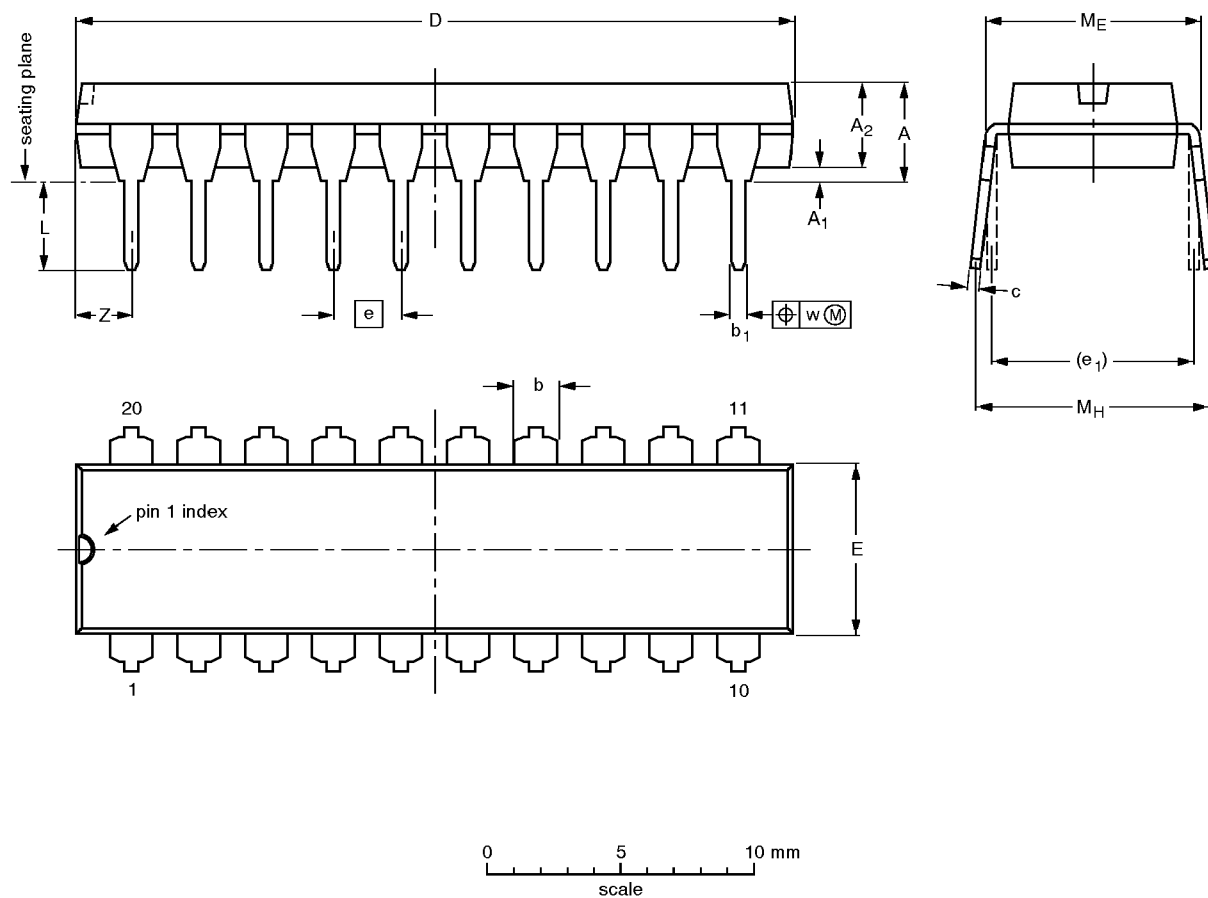
Figure 3. Load circuitry for switching times

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DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



**DIMENSIONS** (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT146-1			SC603			92-11-17 95-05-24

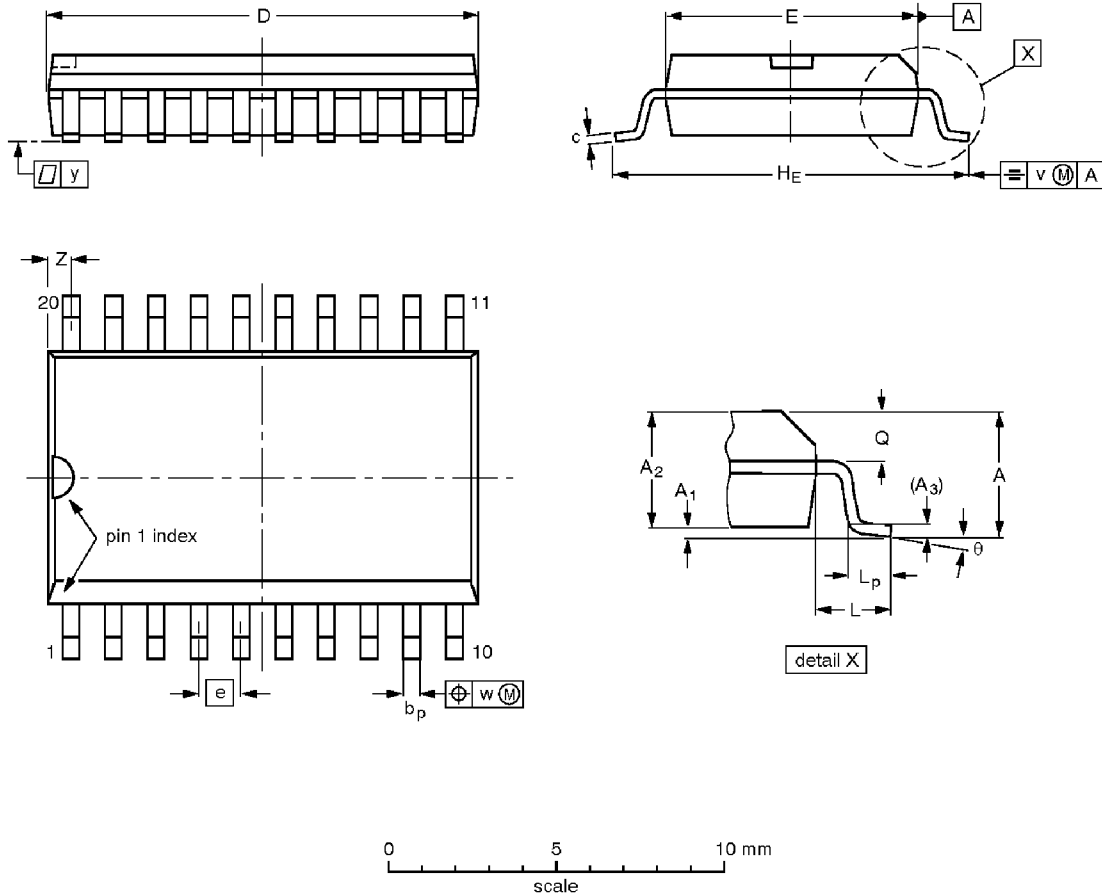


# Octal D-type flip-flop with data enable; positive edge-trigger

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SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



**DIMENSIONS (inch dimensions are derived from the original mm dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

**Note**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

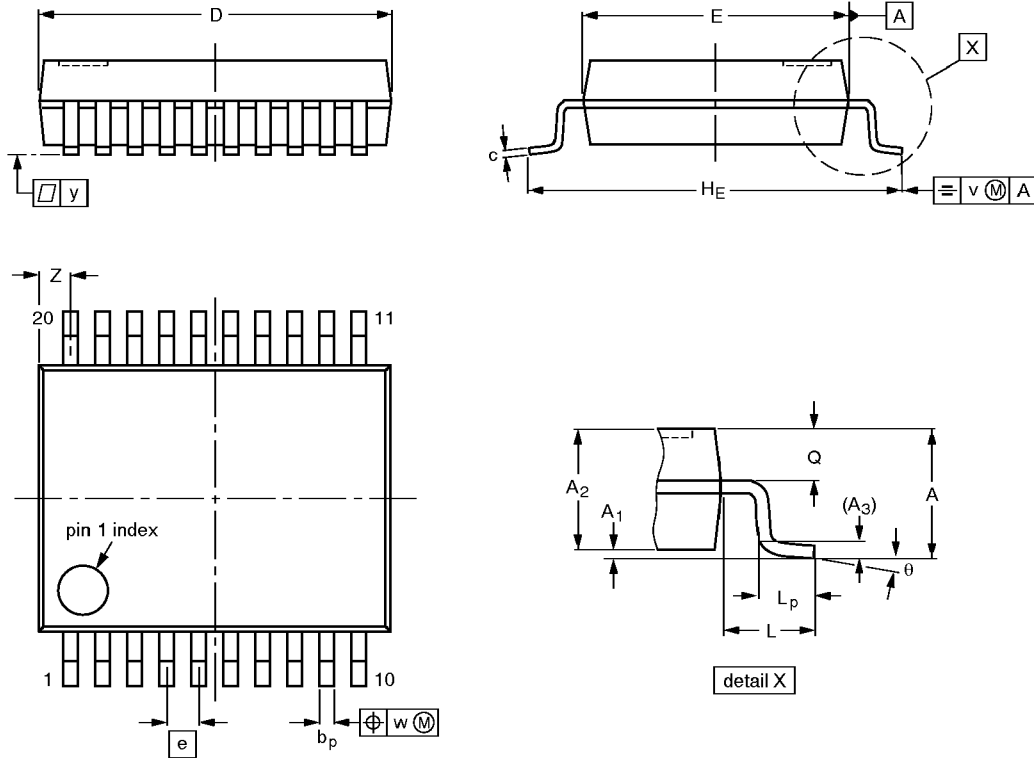
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT163-1	075E04	MS-013AC				92-11-17 95-01-24

# Octal D-type flip-flop with data enable; positive edge-trigger

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SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



**DIMENSIONS (mm are the original dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

**Note**

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

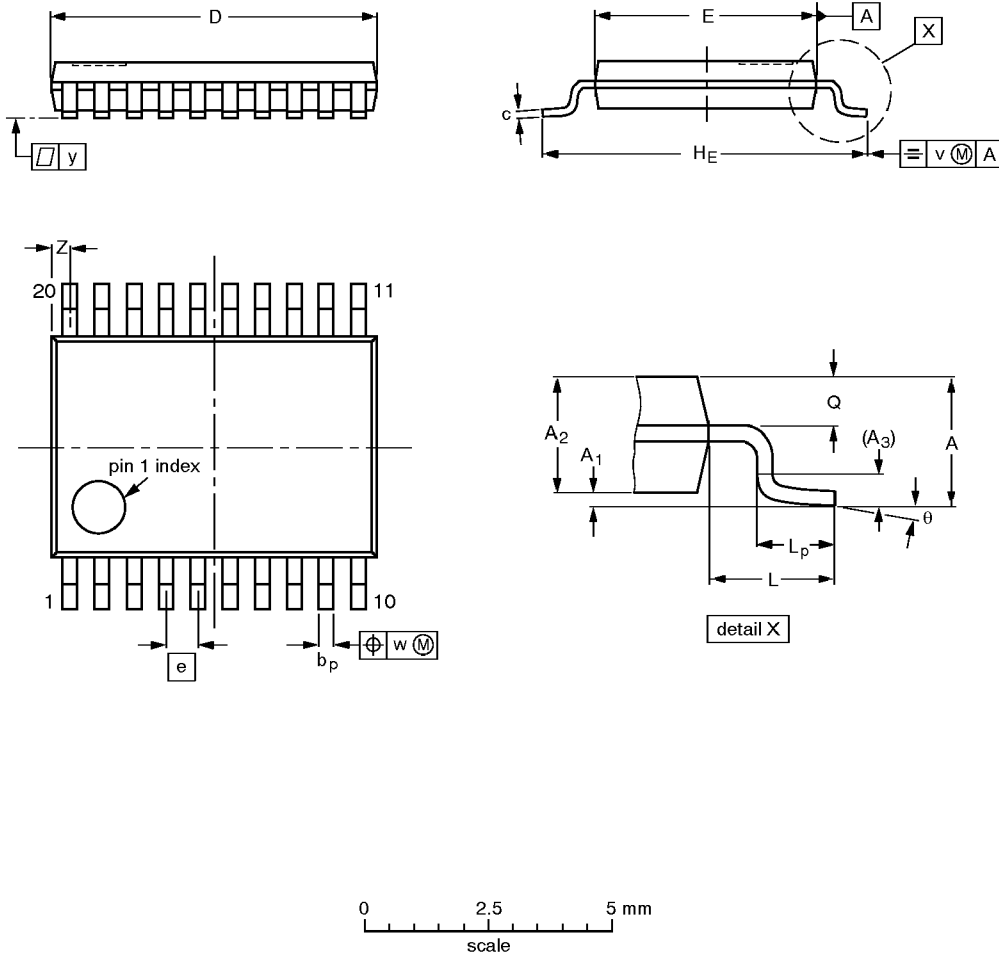
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT339-1		MO-150AE				93-09-08 95-02-04

Octal D-type flip-flop with data enable;  
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TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT360-1		MO-153AC				93-06-16 95-02-04

# Octal D-type flip-flop with data enable; positive edge-trigger

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## DEFINITIONS

Data Sheet Identification	Product Status	Definition
<i>Objective Specification</i>	<b>Formative or in Design</b>	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
<i>Preliminary Specification</i>	<b>Preproduction Product</b>	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
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